

Surface Mount Chip LEDs

Technical Data

HSMx-C650
HSMx-C670
HSMF-C655

Features

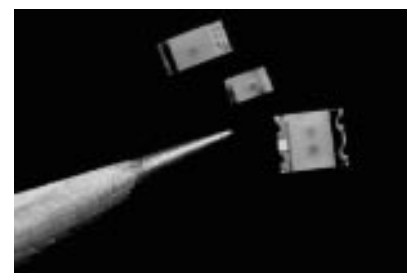
- **Small Size**
- **Industry Standard Footprint**
- **Low Profile**
- **Tinted, Diffused Optics**
- **Compatible with IR Solder Process**
- **Five Colors and Bicolor Available**
- **Available in 8 mm Tape on 7" (178 mm) Diameter Reels**

Applications

- **Push-Button Backlighting**
- **LCD Backlighting**
- **Symbol Backlighting**
- **Front Panel Indicator**

Description

These single and bicolor LEDs are designed in an industry standard package for ease of handling and use. Five different LED colors are available in two compact, low profile, single color packages. The 3.2 x 1.6 mm is an excellent all around package, and the small 2.0 x 1.25 mm package is designed for applications where space is limited. The single color LEDs have

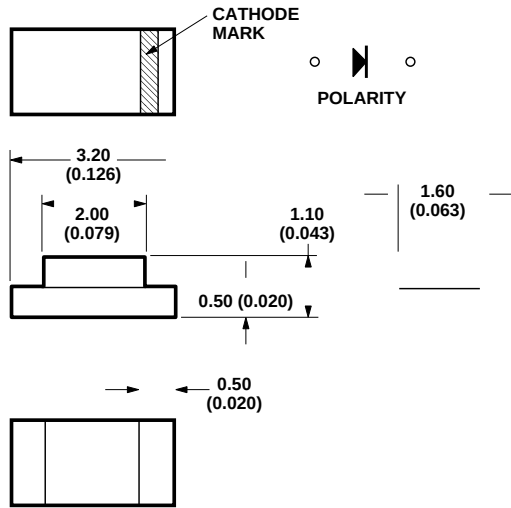


tinted diffused optics. The bicolor package is untinted, diffused.

The small size, low 1.1 mm profile and wide viewing angle make these LEDs excellent for backlighting applications and front panel illumination. They are compatible with IR reflow soldering processes.

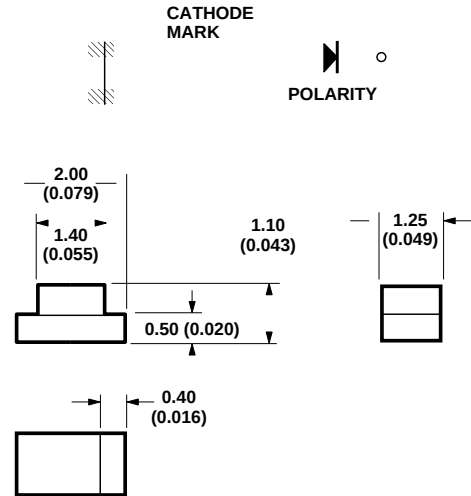
Device Selection Guide

Footprint (mm)	DH AlGaAs Red	High Efficiency Red	Orange	Yellow	Green	Bicolor HER-Green
3.20 x 1.60	HSMH-C650	HSMS-C650	HSMD-C650	HSMY-C650	HSMG-C650	
2.00 x 1.25	HSMH-C670	HSMS-C670	HSMD-C670	HSMY-C670	HSMG-C670	
3.20 x 2.70						HSMF-C655



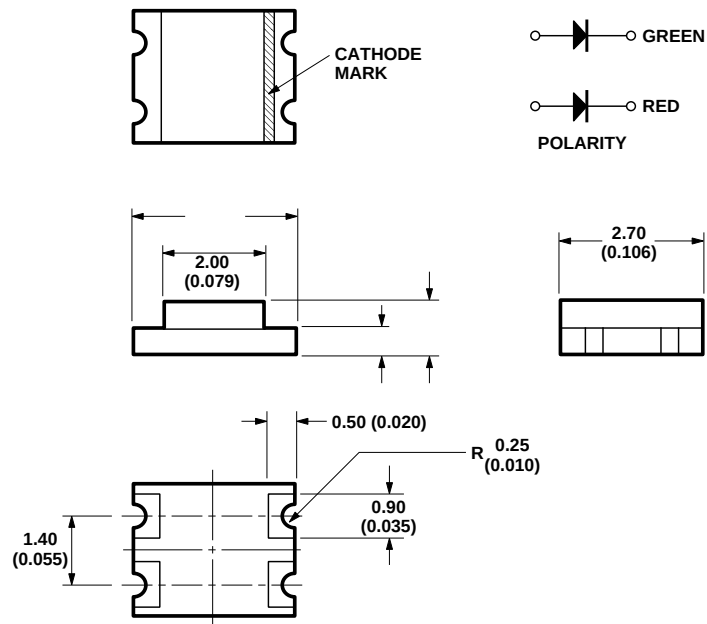
HSMX-C650 Series

[1206]



HSMX-C670 Series

[805]



HSMF-C655

[1210]

Absolute Maximum Ratings at $T_A = 25$

Parameter	HSMF-C655	HSMX-C670	Units
DC Forward Current			
R			
LED Junction Temperature	95	95	°C
Operating Temperature Range	-25 to +80	-25 to +80	°C
Storage Temperature Range	-30 to +85	-30 to +85	°C
Soldering Temperature	See SMT reflow soldering profile, Figure 6		

Notes:

- Derate linearly as shown in Figure 4 for temperatures above 25°C.

$T_A = 25^\circ\text{C}$

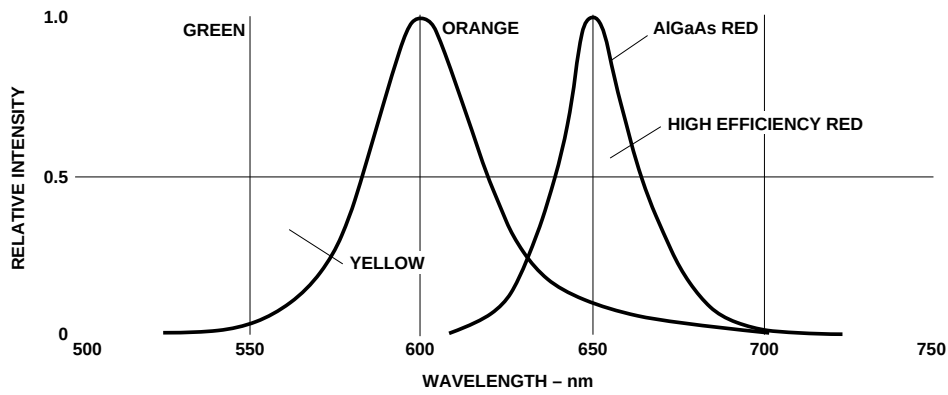
		(mcd) I_F [1]		Wavelength λ_{peak}	Wavelength λ_d [2] (nm)	$2\theta^{1/2}$ Degrees [3]
HSMH-C670						
HSMS-C650 HSMS-C670	High Efficiency Red	1.6	5.0	639	626	155
HSMC-C650 HSMC-C670	Orange	1.6	4.0	606	604	155
HSMY-C650 HSMY-C670	Yellow	1.6	5.0	584	586	155
HSMG-C650 HSMG-C670	Green	4.0	9.0	566	571	155
HSMF-C655	High Efficiency	1.6	5.0	639	626	155
	Green	4.0	9.0	566	571	155

Notes:

- The luminous intensity, I_v , is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the lamp package.
- The dominant wavelength, λ , is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.
- $\theta^{1/2}$ is the off-axis angle where the luminous intensity is 1/2 the peak intensity.
- Chip LEDs are supplied in 8 mm embossed tape on 178 mm (7 in.) diameter reels, with 3000 devices per reel. Minimum order quantity and order increments are in quantity of reels only.

Electrical Characteristics at $T_A = 25$

Part		@ $I_F = 20 \text{ mA}$		@ I_R ^R A	= 0, f = 1 MHz	Thermal Resistance J-PIN °C/W)
HSMH-C650	DH AlGaAs	1.8	2.2	5	46	460
HSMS-C670	Red					250
HSMD-C650	Orange	2.1	2.6	5	4.0	400
HSMY-C670						250
HSMG-C650	Green	2.2	2.6	5	8.0	400
	Red					



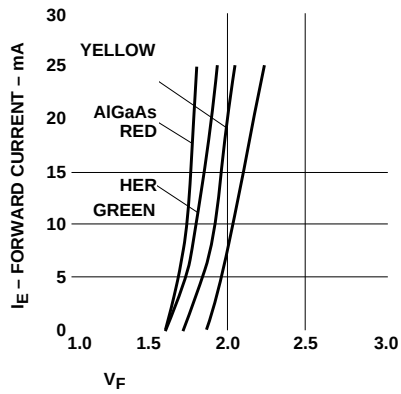


Figure 2. Forward Current vs. Forward Voltage.

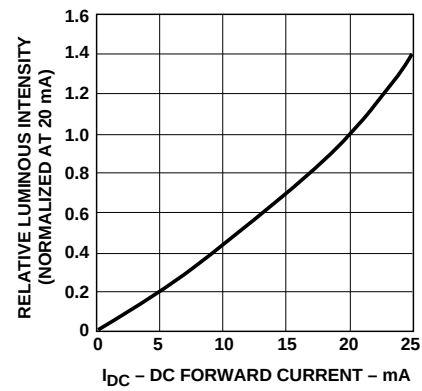


Figure 3. Relative Luminous Intensity vs. DC Forward Current.

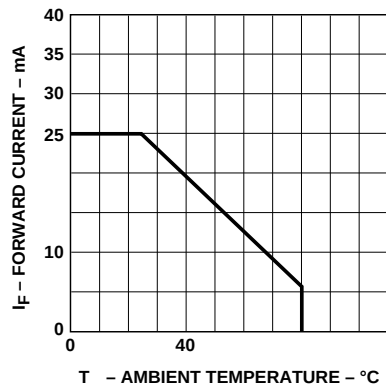


Figure 4. Maximum DC Current vs. Ambient Temperature.

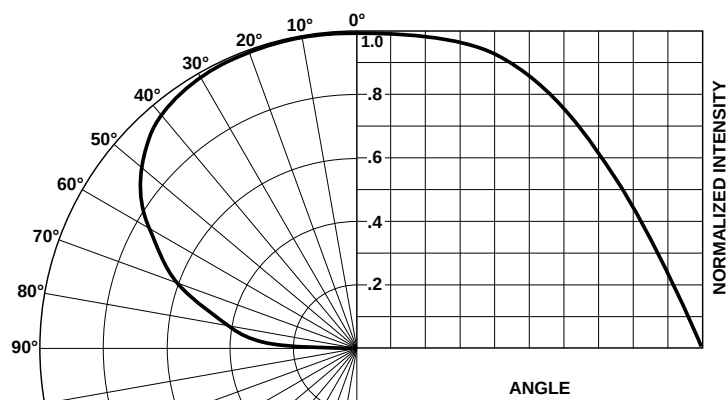


Figure 5. Intensity vs. Angle.

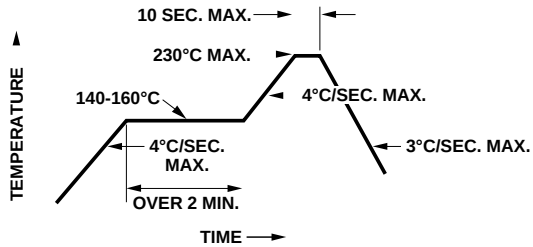


Figure 6. Recommended SMT Reflow Soldering Profile.

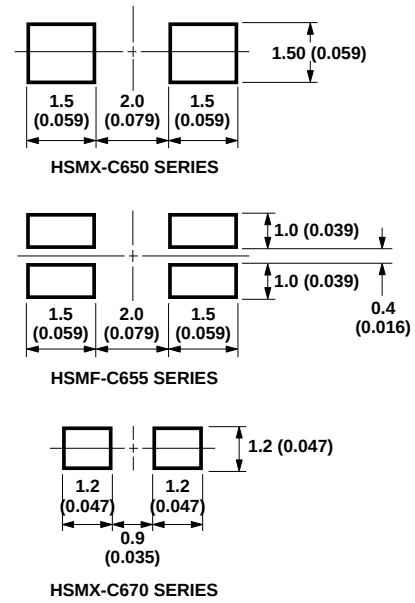


Figure 7. Recommended Solder Patterns.

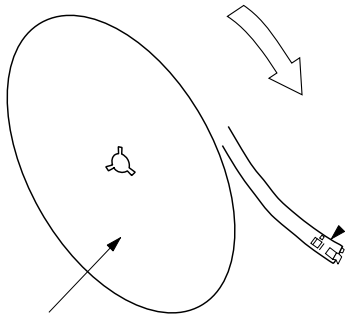


Figure 8. Reeling Orientation.

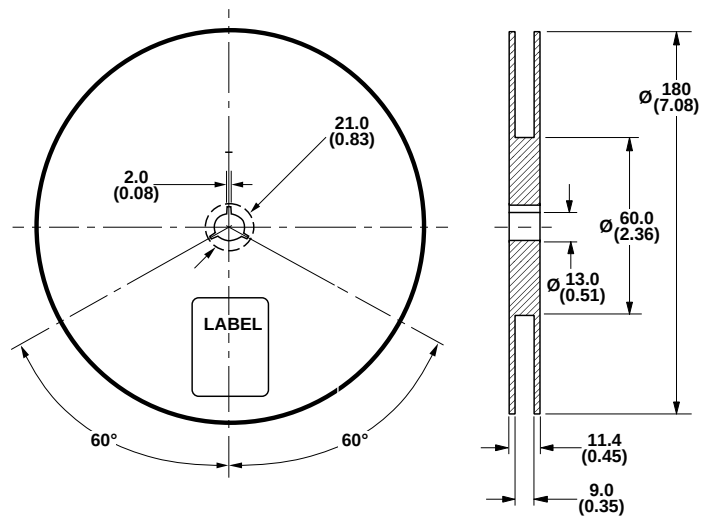


Figure 9. Reel Dimensions.

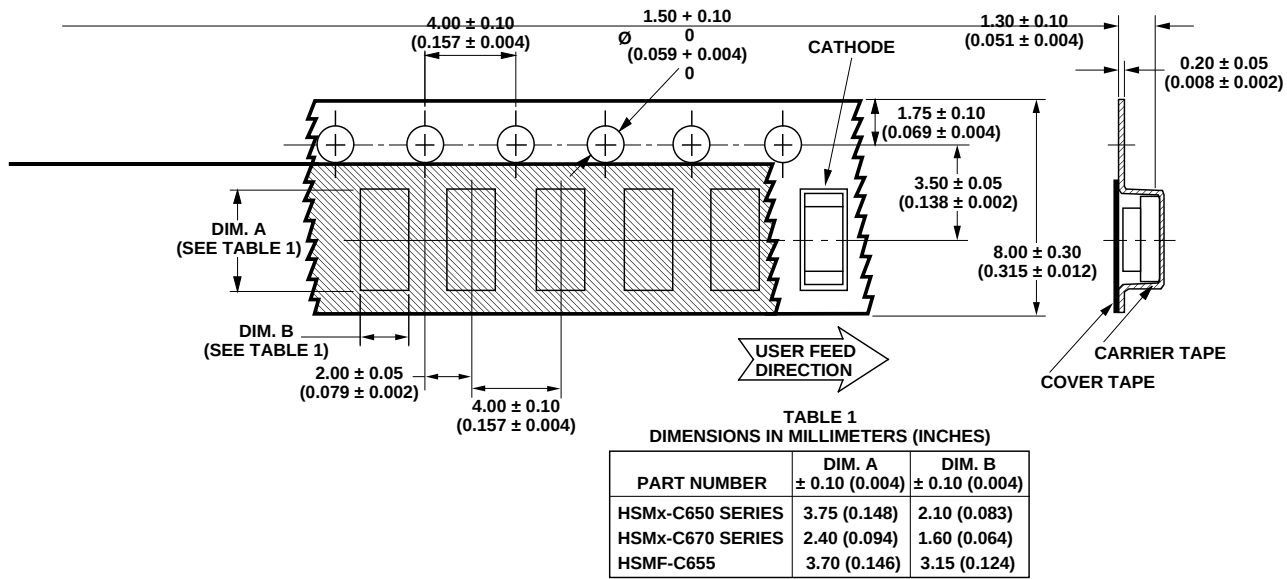


Figure 10. Tape Dimensions.

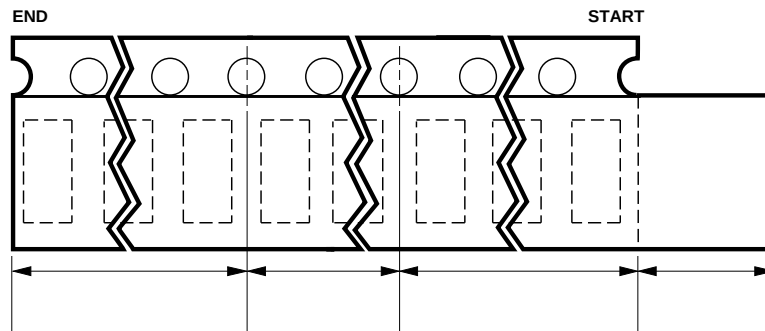


Figure 11. Tape Leader and Trailer Dimensions.

